

30V, 4A, 39mΩ N-channel Power Trench MOSFET

JMTL3406A

Features

- $\bullet \;\;$ Excellent $R_{DS(ON)}$ and Low Gate Charge
- Halogen-free; RoHS-compliant
- Pb-free plating

Applications

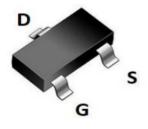
- Load Switch
- PWM Application
- Power Management

Product Summary

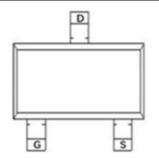
Parameters	Value	Unit
V_{DSS}	30	V
$V_{GS(th)_Typ}$	1.4	V
I _D (@V _{GS} =10V)	4	Α
$R_{DS(ON)_Typ}(@V_{GS}=10V$	29	mΩ
$R_{DS(ON)_Typ}(@V_{GS}=4.5V$	39	mΩ



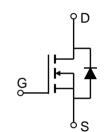




SOT-23 Top View



Pin Assignment



Schematic Diagram

Ordering Information

Device	Marking	MSL	Form	Package	Reel(pcs)	Per Carton (pcs)
JMTL3406A	3406A	3	Tape&Reel	SOT-23	3000	120000

Absolute Maximum Ratings (@ T_A = 25°C unless otherwise specified)

Symbol	Parameter		Value	Unit
V _{DS}	Drain-to-Source Voltage		30	V
V_{GS}	Gate-to-Source Voltage		±20	V
	Continuous Drain Current	T _A = 25°C 4	^	
I _D	Continuous Drain Current	$T_A = 100$ °C	3	 A
I _{DM}	Pulsed Drain Current (1)		Refer to Fig.4	Α
P_{D}	Power Dissipation	$T_A = 25^{\circ}C$	0.9	W
' D	rowei Dissipation	$T_A = 100$ °C	0.4	¬
T_{J}, T_{STG}	Junction & Storage Temperature	Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ⁽²⁾	211	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ⁽³⁾	138	C/ VV



Electrical Characteristics (T_J = 25°C unless otherwise specified)

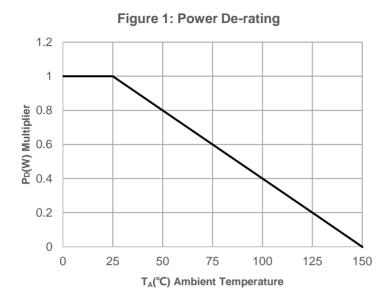
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Cha	nracteristics				ļ	,
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 30V, V_{GS} = 0V$	-	-	1.0	μА
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Cha	racteristics			:		
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.0	1.4	2.5	V
D	Static Drain-Source ON-Resistance ⁽⁴⁾	$V_{GS} = 10V, I_D = 4A$	-	29	38	mΩ
$R_{DS(ON)}$	Static Drain-Source ON-Resistance	$V_{GS} = 4.5V, I_D = 3A$	-	39	65	mΩ
Dynami	ic Characteristics					
R_g	Gate Resistance	f = 1MHz	-	27	-	Ω
C_{iss}	Input Capacitance	24 224	-	243	-	pF
C_{oss}	Output Capacitance	$V_{GS} = 0V$, $V_{DS} = 15V$, $f = 1MHz$	-	40	-	pF
C _{rss}	Reverse Transfer Capacitance	1 - 11/11/2	-	31	-	pF
Q_g	Total Gate Charge	V 0. 45V	-	6	-	nC
Q_{gs}	Gate Source Charge	$V_{GS} = 0 \text{ to } 4.5V$ $V_{DS} = 15V, I_D = 3A$	-	1	-	nC
Q_{gd}	Gate Drain("Miller") Charge	= VDS = 10V, ID = 0/1	-	1	-	nC
				•		
<u>Switchi</u>	ng Characteristics			ı		1
$t_{d(on)}$	Turn-On DelayTime		-	2	-	ns
t _r	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 15V$	-	6	-	ns
$t_{d(off)}$	Turn-Off DelayTime	I_{D} = 3A, R_{GEN} = 2.7 Ω	-	24	-	ns
t _f	Turn-Off Fall Time		-	14	-	ns
Body D	iode Characteristics					
Is	Maximum Continuous Body Diode Forward	Current	-	-	4	А
I_{SM}	Maximum Pulsed Body Diode Forward Cur	rent	-	-	15	Α
V _{SD}	Body Diode Forward Voltage	$V_{GS} = 0V$, $I_S = 4A$	-		1.2	V
trr	Body Diode Reverse Recovery Time	1 2A di/d+ 400A/:	-	5	-	ns
Qrr	Body Diode Reverse Recovery Charge	$I_F = 3A$, di/dt = 100A/us	-	1.5	-	nC

Notes:

- 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
- 2. $R_{\theta JA}$ is measured with the device mounted on a minimum recommended pad of 2oz copper FR4 PCB.
- 3. $R_{\theta JA}$ is measured with the device mounted on a 1inch $^{\!2}$ pad of 2oz copper FR4 PCB.
- 4. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 0.5%.



Typical Performance Characteristics



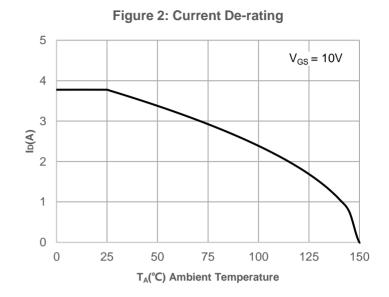
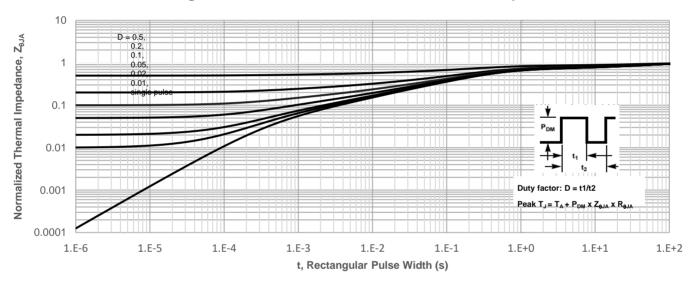
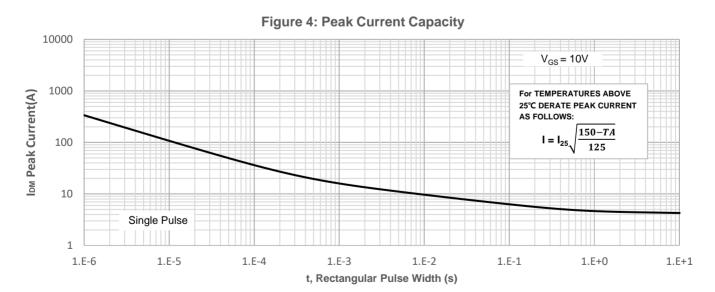


Figure 3: Normalized Maximum Transient Thermal Impedance







Typical Performance Characteristics

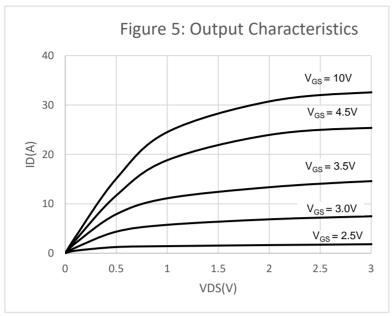


Figure 6: Typical Transfer Characteristics

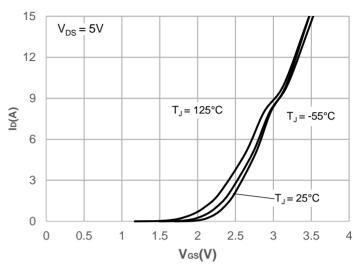


Figure 7: On-resistance vs. Drain Current

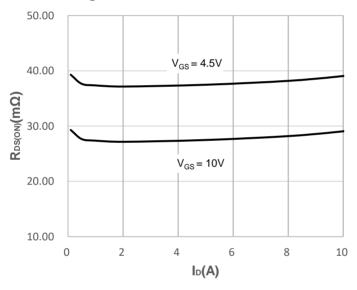


Figure 8: Body Diode Characteristics

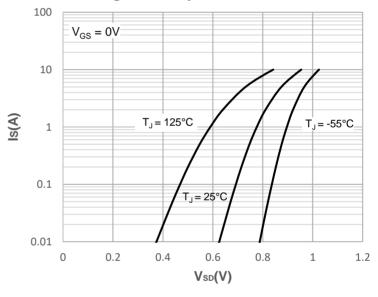


Figure 9: Gate Charge Characteristics

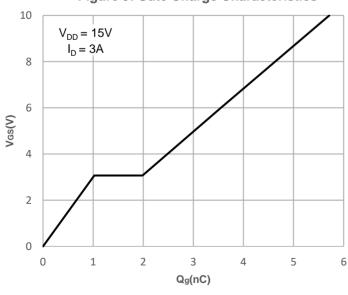
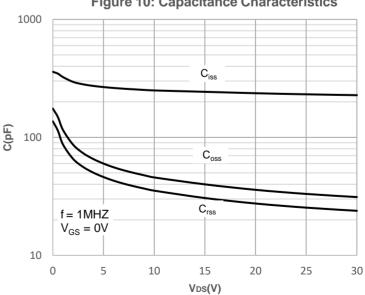


Figure 10: Capacitance Characteristics





Typical Performance Characteristics

Figure 11: Normalized Breakdown voltage vs. Junction Temperature

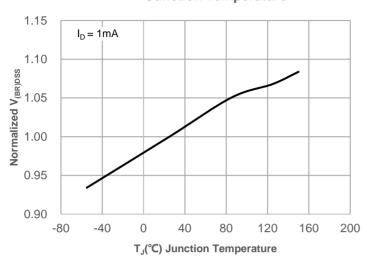


Figure 13: Normalized Threshold Voltage vs. Junction Temperature

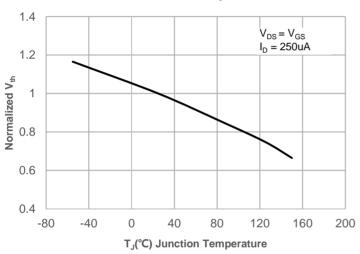


Figure 15: Maximum Safe Operating Area

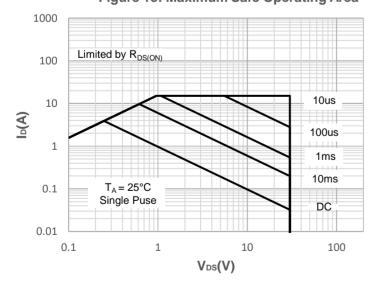
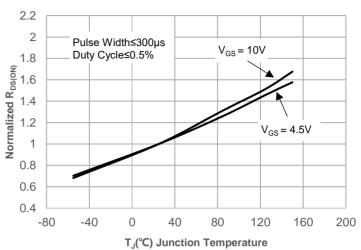
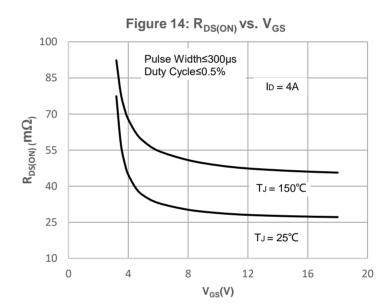


Figure 12: Normalized on Resistance vs. Junction Temperature







Test Circuit

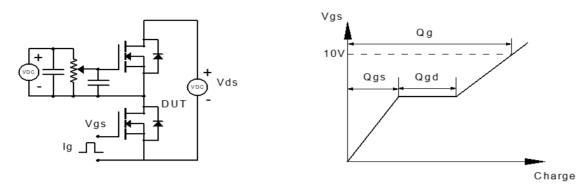


Figure 1: Gate Charge Test Circuit & Waveform

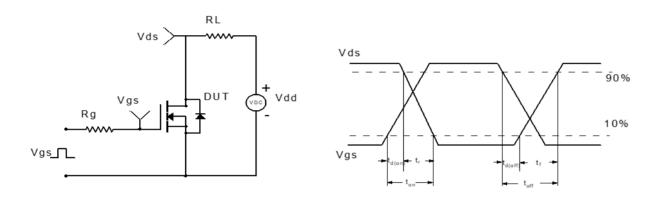


Figure 2: Resistive Switching Test Circuit & Waveform

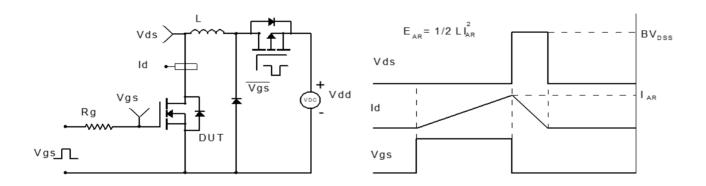


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

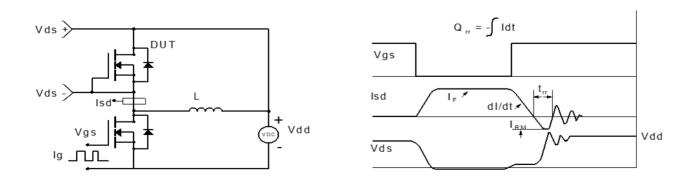
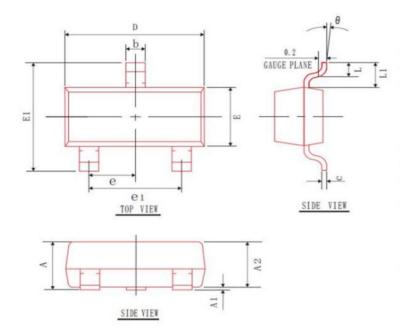


Figure 4: Diode Recovery Test Circuit & Waveform



Package Mechanical Data(SOT-23)



SYMBOL	MIN	NOM	MAX
A	0.90	1.05	1.20
A1	0.00	0.05	0.10
A2	0.90	1.00	1.10
b	0.30	0.40	0.50
C	0.08	0. 10	0.15
D	2.80	2.90	3.00
E	1. 20	1.30	1.40
E1	2. 30	2.40	2.50
L	0.30	0.40	0.50
θ	0°	5°	10°
L1	0. 55 REF		
е	0. 95 BSC		
e1	1 90 RFF		

COMMON DIMENSIONS (INTTS OF WEASURE-mm)

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